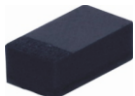


MATERIAL DATA SHEET

Material #	CDSER series(0503) (Halogen Free)	
Product Line	Discrete Devices	
Date	2014/1/27	
Rev. date	H	

COMPONENT DETAILS

No.	Construction element	Material group	Material weight (mg)	Material	CAS if applicable	Average mass (%)	Sum(%)	Traces
1	FR-4 Board	Substrate/ Terminal	0.231	Copper	7440-50-8	58.86%	16.27%	
				Nickel	7440-02-0	3.12%		
				Aurum	7440-57-5	0.09%		
				Lead	7439-92-1	0.002%		
				Continuous Filament Fiber Glass	65997-17-3	37.93%		
2	Wafer	Diode	0.029	Silicon	7440-21-3	90.40%	2.04%	
				Aluminum	7429-90-5	0.10%		
				Gold	7440-57-5	9.50%		
3	Al wire	Conductor	0.001	Aluminium	7429-90-5	>99%	0.07%	
				Silicon	7440-21-3	<1%		
4	Silver paste	Welding	0.006	Modified Epoxy Resin	29690-82-2	5~25%	0.42%	
				Silver	7440-22-4	76~85%		
				Imidazole	827-43-0	1~4%		
				Amide	461-58-5	1~4%		
5	Molding Compound	Outer	1.153	Silica	60676-86-0	70~90%	81.20%	
				Epoxy Resin	29690-82-2	6~16%		
				Phenolic Resin	9003-35-4	5~15%		
				Carbon Black	1333-86-4	0.1~1%		
Total weight			1.42					